<u>Lowering Material and Energy Usage</u> <u>during Dry-down of Ultra-pure Gas</u> <u>Delivery Systems*</u>

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Outline

- Background
- Research objectives and ESH implications
- Parts need to be cleaned in UHP gas delivery systems
- Potential major contamination sources in UHP gas delivery systems
- Experimental and process models
 - 1. Pipe wall
 - 2. Dead leg
 - 3. Back-diffusion
- Comprehensive model & its application
- Conclusion
- Future work and Acknowledgements

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Objectives

• Develop methods to analyze contamination *introduction* and *removal* in ultra-pure gas delivery systems

ESH Impacts

- Contamination of gas distribution systems during operation or at start-up is a major source of wasted time, materials, and energy.
- Significant reduction in purging time and gas usage can be accomplished by optimizing purging and cleaning processes, based on the project results.

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What needs to be cleaned?



Cleaning/purging processes for these contaminated parts fast or slow?

Moisture Dry-down --- EPSS Pipe

Moisture Detector: APIMS



Moisture removal on stainless steel pipe is a slow process.

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Moisture Dry-down ---- MFC

Initially the MFCs were equilibrated with 200 ppb of moisture in N_2 at 25 °C;

Isothermal Purge with 0.2 ppb purge gas , purge flow rate: 500 sccm



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Moisture Dry-down --- Other Components

<u>Valves</u>: please refer to literature*

Filters:

Moisture Dry-down of Different Types of Filters **

Filters (Surface area/m ²)	Ceramic (13.65)	Metallic (1.19)	Polymeric A (0.52)	Polymeric B (0.96)	Polymeric C (1.5)
Concentration (ppb)	180	300	100	150	180
	20	20	20	20	20
Time (min)	580	110	12	65	42

* Seksan Dheandhanoo, James H. Yang, and Michael D. Wagner. Modeling the Characteristics of Gas System Dry-down. Solid State Technology, Vol. 44 No. 6, June 2001, p.125.

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** Asad M. Haider, Ce Ma, and Farhang Shadman, Interactions of Ceramic. Metallic and Polymeric Filters with Gaseous Contaminants. Proceedings of Institute of Environmental Sciences, 1993, p.158.



Diffusion from dead legs and back diffusion from ambient or contaminated zones can cause contamination to the whole gas delivery system.

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Experimental Procedure



Temporal profile of moisture isothermal absorption/desorption processes

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Dynamics of Adsorption

Test Section: EPSS pipe with 1.5 inch OD and 14 inch length. Initially the system was baked at 200 °C. Challenge at four different temperatures with moisture concentration at 181 ppb and flow rate: 350 sccm



Dynamics of Desorption

Test Section: EPSS pipe with 1.5 inch OD and 14 inch length. Initially the system was equilibrated with 181 ppb of moisture at four different temperatures, then isothermal purged with 0.2 ppb purge gas and flow rate: 350 sccm



Process Model I --- A Single Pipe

Bulk Gas

 C_{S}

Pipe Wall

Change of moisture concentration on pipe wall:

$$\frac{\partial C_s}{\partial t} = k_{ads} C_g (S_0 - C_s) - k_{des} C_s$$

Change of moisture concentration in gas phase:

$$\frac{\partial C_g}{\partial t} = D_L \frac{\partial^2 C_g}{\partial z^2} - u \frac{\partial C_g}{\partial z} + \frac{A_S}{V} (k_{des} C_S - k_{ads} C_g (S_0 - C_S))$$

 C_s : moisture concentration on pipe wall, mol/cm²; C_s : moisture concentration in gas, mol/cm³; k_{ads} : adsorption rate constant, cm³/mol/s; k_{des} : desorption rate constant, 1/s S_0 : site density of surface adsorption, mol/cm²; D_L : dispersion coefficient, cm²/s; u: velocity, cm/s; A_s : surface area of pipe wall, cm²; V: volume of pipe, cm³

Model Validation and Parametric Estimation

Test Section: EPSS pipe with 1.5 inch OD and 36 inch length. Initially the whole system was equilibrated with different concentrations of moisture at 25 °C. Isothermal purge with 0.2 ppb purge gas; purge gas flow rate: 350 sccm



Application of Process Model I

Moisture Distribution along Pipe During Purging Process

Test Section: EPSS pipe with 1.5 inch OD 36 inch length. Initially the whole system was equilibrated with 181 ppb at 25 °C. Isothermal purge with 0.2 ppb and 350 sccm purge gas



After 3 hrs of purging, roughly only 50% of the total moisture absorbed on pipe wall has been removed



Application of Process Model II- Effects of a Dead Leg Initially the whole system was equilibrated with 200 ppb of moisture at 25 °C. Isothermal purge for 1 hr with 0.2 ppb purge gas, and purge gas flow rate: 500 sccm Cout Dead Leg; 0.25 in, 10 cm C_{in} Main Pipe, 1.5 in, 1m 16 50 14 45 Moisture Conc., ppb with Dead Leg 12 **40** with Dead Leg 10 Coup, ppb 35 No Dead Leg 8 30 $\Delta Cout \sim 1.6 ppb$ 6 25 4 20 No Dead Leg 2 15 0 10 0.2 0.4 0.6 0 0.8 1 0 10 30 50 20 40 60 Length, m Purge Time, min Moisture profile along the main pipe after 1 hr purge C_{out} vs. purge time 19 SRC/Sematech Engineering Research Center for Environmentally Benign Semiconductor Manufacturing

Process Model III - Back Diffusion Bulk Gas 1: Bulk Convection; 2: Surface Diffusion; 3: Molecular Diffusion $C_{g0} >> ppb$ levels

Bulk gas:

$$D_L \frac{\partial^2 C_g}{\partial z^2} - u \frac{\partial C_g}{\partial z} + \frac{A_S}{V} (k_{des} C_S - k_{ads} C_g (S_0 - C_S)) = 0$$

Surface reaction and surface diffusion:

$$D_{S} \frac{\partial^{2} C_{S}}{\partial z^{2}} + k_{ads} C_{g} (S_{0} - C_{S}) - k_{des} C_{S} = 0$$

 D_s : Surface diffusion coefficient, cm²/s; C_{g0} : ambient moisture concentration , >> 1 ppb;

<u>Application of Process Model III –</u> <u>Contaminated Zones of Laterals</u>







Model Application- Comprehensive Model Example 1

Sample: One main pipe with one dead leg and one lateral. Initially the whole system was equilibrated with 200 ppb of moisture at 25 °C. Isothermal purge for 1 hr with 1 ppb purge gas, and total purge gas flow rate: 5000 sccm







Parametric Study – Purge Flow Rate

Test Section: EPSS pipe with 1.5 inch OD and 36 inch length. Initially the whole system was equilibrated with 181 ppb of moisture at 25 °C. Isothermal purge with 0.2 ppb purge gas



Parametric Study – Purge Gas Purity

Test Section: EPSS pipe with 1.5 inch OD and 36 inch length. Initially the whole system was equilibrated with 181 ppb of moisture at 25 °C. Isothermal purge with 350 sccm purge gas





System Disturbance – Pressure Fluctuation

Figure was provided by Intel Fab. Actual values on both Y-axes were removed due to confidentiality



H₂0 in Bulk O₂ End of Main Pipe



Conclusion

- Cleaning of moisture contaminated UHP gas delivery system is a slow process. The purging process must be optimized.
- Different components (transfer pipes, filters, flow controllers, valves, regulators) have different moisture outgassing rates. Smaller interior surface area and surface finishes with less roughness are desired.
- Dead leg and back diffusion can cause contamination to the main stream. The number of dead legs should be minimized. Heating dead legs can partially decrease contamination from the dead leg. At laterals, only critical flow rates are required to block back diffusion.
- The comprehensive model in this research can help us to optimize purging processes with minimized time and cost. It also can allow us to predict moisture removal in main pipes and sub-pipes.
- System perturbation should be avoided.

Future Plans

- Set up mathematical modeling for valves, regulators and MFCs (figuring out the <u>equivalent length</u> as a pipe); improve the comprehensive model.
- More study on system perturbation.
- Continue working with Intel; initiate similar applications and studies for other members; prepare a software package for purging/cleaning scenario study.

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